

ABSTRACT OF THE DISCLOSURE

~~An objective of this invention is to provide an~~ An epoxy resin composition for encapsulating a semiconductor chip, which has good flowability without deterioration in curability. Specifically, ~~this invention provides a resin composition for encapsulating a semiconductor chip containing an epoxy resin (A), a phenol resin (B), an inorganic filler (C) and a curing accelerator (D) as main components, comprising and further containing~~ a silane coupling agent (E) in 0.01 wt% to 1 wt% both inclusive of the total amount of the epoxy resin composition and Compound (F) contains two hydroxyl groups combined with each of adjacent carbon atoms ~~comprising said naphthalene~~ in an aromatic ring in more than or equal to 0.01 wt% of the total amount of the epoxy resin composition.